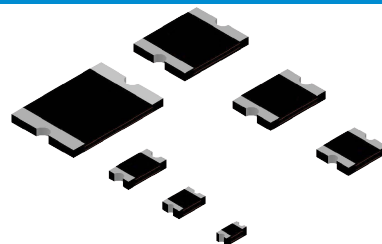


DW-1812-150-33 Surface Mount PPTC Devices

Features & Applications

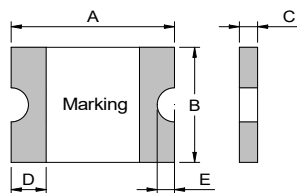
- Compact design saves board space
- RoHS compliant and lead-free
- Halogen-free
- Fast response to fault current
- Symmetrical design
- USB port protection - USB 2.0, 3.0&OTG
- HDMI 1.4 Source protection
- PDAs / digital cameras
- Game console port protection
- PC motherboards-plug and play protection



Electrical Characteristics

Part Number	I-hold	I-trip	Vmax	Imax	Pd typ	Max. Time to trip		R0 min	R1 max
						Current	Time		
	(A)	(A)	(Vdc)	(A)	(W)	(A)	(Sec.)	(Ω)	(Ω)
DW-1812-150-33	1.50	3.00	33.00	40.00	0.80	8.00	1.50	0.03	0.15

Product Dimensions(mm) (size of 1812)



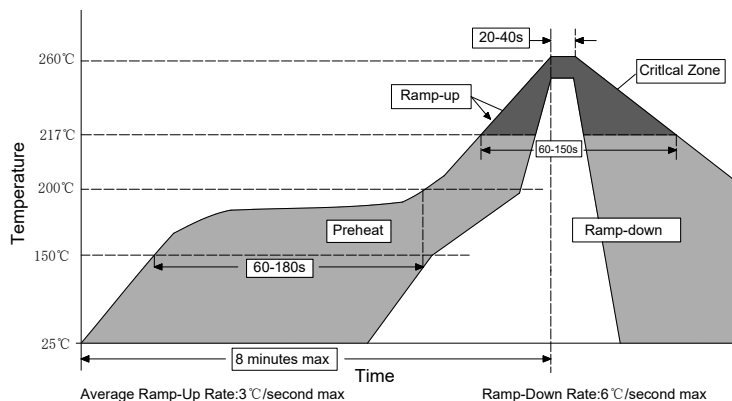
Part Number	A		B		C		D		E	Marking	Quantity pcs/R
	Min	Max	Min	Max	Min	Max	Min	Max	Min		
DW-1812-150-33	4.37	4.73	3.07	3.41	0.85	1.35	0.30	1.20	0.20	D150 33	1000

Thermal Derating

Recommended hold current(A) at ambient Temperature(°C)

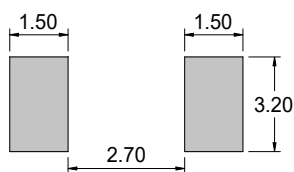
DW-1812-150-33	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold current (A)	2.06	1.93	1.79	1.50	1.28	1.10	1.02	0.80	0.68
Trip current (A)	4.12	3.86	3.58	3.00	2.56	2.20	2.04	1.60	1.36

Soldering Parameters



- ◆ All temperature refer to topside of the package, measured on the package body surface
- ◆ If reflow temperature exceeds the recommended profile, devices may not meet the performance requirements
- ◆ Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead
- ◆ Recommended maximum paste thickness is 0.25mm (0.010inch)
- ◆ Devices can be cleaned using standard industry methods and solvents

Recommended Pad Layout(mm) & Physical Specifications



Terminal Material	Tin-Plated Nickle-Copper (Solder Material: Matte Tin (Sn))
Lead Solderability	Meets EIA Specification RS186-9E, ANSI/J-STD-002 Category 3.

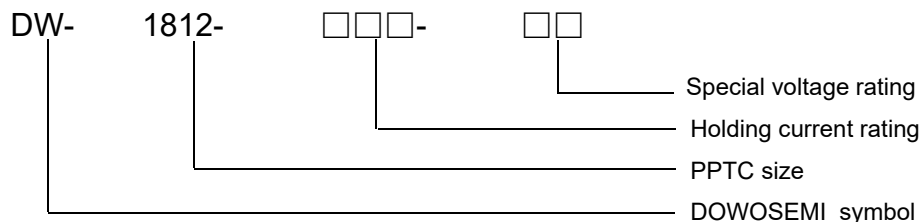
Environmental Specifications

Operating Temperature	-40 °C to +85 °C
Maximum Device Surface Temperature in Tripped State	125°C
Passive Aging	+85 °C, 1000 hours ; ±5 % typical resistance change
Humidity Aging	+85 °C, 85 % R.H. 1000 hours; ±5 % typical resistance change
Thermal Shock	MIL-STD-202, Method 107; +85 °C to -40 °C, 20 times;-30 % typical resistance change
Solvent Resistance	MIL-STD-202, Method 215 ; No change
Vibration	MIL-STD-883, Method 2007, Condition A; No change
Moisture Sensivity Level	Level 1, J-STD-020
Storage Conditions	+40 °C Max. 70% RH Max. Packed in original packaging.

Test Procedures & Requirements

No.	Test	Test Conditions	Accept/Reject Criteria
1	R0 min	Resistance measurement at 25°C	$R0min \leq R \leq R1max$
2	R1 max	Resistance measurement one hour after post trip	$R0min \leq R \leq R1max$
3	I-hold	Hold rated current 1800 second without trip, @ 25°C	No trip
4	I-trip	Device must trip within 900 second under rated current, @25°C	Trip
5	Max. time to trip	At specified current, 25 °C	$T \leq \text{max. time to trip (seconds)}$
6	Trip Cycle Life	Vmax, Imax, 100 cycles	No arcing or burning
7	Trip Endurance	Vmax,Imax 24 hours	No arcing or burning
8	Solderability	ANSI/J-STD-002	95 % min. coverage

Part Ordering Number System





Application Notice

1. Operation of these PPTC devices beyond the stated maximum ratings could result in damage to the devices and lead to electrical arcing and/or fire.
2. These PPTC devices are intended to protect against the effects of temporary over-current or over-temperature conditions and shall not be taken for use as switch, Multiple times tripping shall lower the PPTC hold current.
3. Exposure to lubricants, silicon-based oils, solvents, gels, electrolytes, acids, and other related or similar materials may adversely affect the performance of PPTC devices.
4. Circuits with inductance may generate a voltage above the rated voltage of the PPTC device and should be thoroughly evaluated within the user's application during the PPTC selection and qualification process.
5. Please do not smash, clamp, pull, dent or twist by tool during assembling process, as they may result in the PPTC damage.
6. The above parameters are concluded from one time of reflow soldering processing the PPTC. If there is any further heat generated process like injection or dispensing at the customer's premise, the aforementioned parameters will decrease at certain degree. Therefore the verification test to be conducted is necessary.
7. When mounting or using PPTC, all injection molding materials, curing adhesives, UV glue, silica gel and cleaning agents or solvents must be tested in terms of application parameters e.g. temperature, time, and etc to ensure the consistency between the product and the processing before use.
8. The PPTC is thermal sensitive device. It is recommended not to design any heat source devices around it to reduce the outside heat source impact.
9. SMD PPTC is designed for SMT processing which applies reflow soldering. Please refer to the recommended curve for reference. If the reflow soldering temperature exceeds the recommended value, the PPTC might be damaged. Hand welding PPTC is prohibited, if there is soldering iron welding process, it is suggested that the welding position should be more than 1.5mm away from PPTC, the welding tool temperature should be lower than 350°C, and the contact time between soldering iron and solder joint should not exceed 3sec.
10. In charging terminal application, PP type material is recommended to use as inner membrane and TPE and PVC type material is inhibited.